TPC-B610

Modular TPC - Computing Box Module with Intel® 10th Gen. Core[™] i CPU Socket (LGA1200)



Features

- High Performance Computing Box powered by Intel[®] 10th Gen. Core™ i CPU Socket (LGA1200) with fanless design
- 10+ x Panel Modules (IP66) ranging from 15" to 23.8" in selection
- Dual Channel Memory slots (DDR4) support up to 64GB in total
- Comprehensive I/Os, including 6 x USB, 2 x COM, 2 x RJ45...etc
- Supports Expansion via 1 x PCle x16, ,1 x PCl or PCle x 4, 1 x mPCle, 2 x M.2 (NVMe, SATA, 5G)
- Supports Storage via 2 x 2.5" HDD/SSD (RAID 0/1), 2 x M.2 (2242/2280)

1 x M.2 M key 2280 (SATA or NVMe PClex4)**

- Supports Fieldbus protocols/GPS/GPRS/Wi-Fi capabilities via iDoor technology
- Supports Diverse system I/O, DIO, PoE...etc. via iDoor technology
- Supports TPM 2.0 hardware security

Introduction

Advantech's TPC-B610 is the highest performance Panel PC solution to date for your future-proof Industry 4.0 application. This Modular Computing Box, with its iconic fanless design, is powered by 10th Gen. Intel Core i Socket (LGA1200), a total of 64GB DDR4, comprehensive I/Os including 6 x USBs, greatest expansion via PCIe x16 and bountiful Storage through M.2 SATA/NVME and 2 x 2.5" HDD/SSD slots, living up to your high-end processing and calculation demands. With an easy pairing with Panel Module, a premium Panel PC system with IP66-grade, ranging from 15" to 23.8" up to FHD resolution, is born to meet your corporate expectation.

Storage Slot*

w/ FPM-D15W-FHE

w/ FPM-D18W-FCF/B

w/ FPM-D21W-CE/BE

w/ FPM-D21W-HF

w/ FPM-D24W-CE/E

98W

90W

85W

115W

94W

212W

204W

199W

229W

208W

15.6'

18.5

21.5

21.5

23.8

1920x1080

1920x1080

1920x1080

1920x1080

1920x1080

*For other Modular Series TPC/FPM family members, please find 'TPC-B520', 'TPC-B520L', and 'TPC-B300' on Advantech's official website.

Specifications

General

| | | 5 | | 1 | | | , |
|----------------------------------|--|---|--------------|-----------------|-----------------------------|---------------------|------------------|
| BIOS | AMI UEFI | | | | (6) 2242 (SAI | A) A Max Zmm): | ** |
| Certification | BSMI, CCC, CE, FCC Class A, CB/UL | 1/0 | | 2 X Z.0 30 | | A, IVIAX. / IIIIII) | |
| Cooling System | Fanless design | ■ I/U | | T X KS-232 | 2/422/485 (00 | JIVI I) | |
| Dimensions (W | x H x D) 269 x 224 x 70 (mm) | | | T X KS-232 | | | |
| Enclosure | Dio cast aluminum allov | | | 5 X USB 3. | 2 (Gen T) | | |
| Mounting | VECA Mount Desites Well as Desit Mount | | | I X USB Z. | U | | |
| | VESA MOUTH, DESKLOP, WAIT OF PAHEI MOUTH | | | 1 x Dispidy | /port 1.2 inc.out/Mic.ir | | |
| OS Support | Win10 LISC, Linux | | | T X AUUIO I | The out/whic h | I | |
| Security | TPM 2.0 (built-in) | Environment | | | | | |
| Power Consum | ption Typ. 74W; Max. 187W (without Panel Module) | | | | | | |
| • Power Input | $24 V_{DC} \pm 20\%$ | Humidity | | 95% RH @ | ₽40°C, non-c | ondensing | |
| Watchdon Time | r 15-255 sec (system) | Ingress Protection | on | IP66 (for o | ptional panel | module with "F | Panel Mount") |
| Woight (Not) | 4 5 kg (0.02 lbs) | Operating Temp | erature | 35W CPU: | -10~50°C (14 | 4~122°F) (w/ 0 |).7 m/s airflow) |
| - weight (Net) | 4.5 Kg (3.52 lb3) | | | 65W CPU: | -10~40°C (14 | 4~104°F) (w/ C |).7 m/s airflow) |
| System Hardwai | 'e | Storage Temperative | ature | -20~70°C | (-4~158°F) | | |
| CPU | Intel® 10 th Gen. Core™ i Socket CPU (LGA1200)*** | Vibration Protect | tion | With SSD: | 1 Grms (5 ~ 5 | 600 Hz) | |
| Memory | Dual channel DDB4 SO-DIMM | | | (Operating | , random vibra | ation) | |
| moniory | (Each channel supports up to 32G, 2933 MHz) | Note 1: Operating Temperat | ture is base | ed on 1 x Indus | trial SSD withou | PCI expansion ca | ards. When |
| | 2 v 10/100/1000BASE_T (LAN A: i210 LAN B: i210) | Note 2: IP66 is applicable f | or Panel M | lount | 15-10~40 0 1011 | Journ types of GPU | 5. |
| Erin Expansion Clot | 1 x PClo x16 | | or r anor n | iount. | | | |
| · Expansion Sion | 1 x PCI** | Power Consumpt | ion wi | th Panel | Module | | |
| | 1 x PCle x4** | Itom | Power C | onsumption | Saroon Sizo | Population | Account Patio |
| | 1 x Full-size mini PCle | nem | Туре | Max. | Screen Size | nesolution | Aspect hallo |
| | 1 x M 2 B key 3025 (5G) USB3 | TPC-B610 | 73W | 187W | N/A | N/A | N/A |
| | 1 x SIM card slot | W/ FPM-D151-GE/BE | 07W | 211W | 15 | 1024X/68 | 04:03 |
| | | w/ FPM-D17T-CF/RF | 89W | 203W | 17" | 1280x1024 | |
| | | w/ FPM-D19T-CE | 87W | 201W | 19" | 1280x1024 | 05:04 |
| | | w/ FPM-D15W-FCE/FBE | 89W | 203W | 15.6" | 1920x1080 | |
| | | | | | | | |

*TPC-B610 supports only wide temperature (~85°C or wider) M.2 storage.

**PCI and M.2 2280 (SATA) is only for TPC-B610H-A00A.

**PClex4, NVMe, RAID 0/1 are only for TPC-B610W-A00A.

***CPU Power was limited to 35W via BIOS default for fanless support.

AD\ANTECH Modular Panel PCs

16:09

TPC-B610



Rear View



A. PCI expansion slots B. 2.5" HDD/SSD slots C. Displayport 1.2 D. Power Receptor E. USB (5 x 3.2, 1 x 2.0) F. Remote Power G. RS-232/422/485 (COM 1), RS-232 (COM 2) H. RJ45 (10/100/1000BASE-T) I. Audio line out/Mic in

Note 1: The max, dimension of PCI expansion cards supported is 191 x 111.15 x 34.80 mm. Note 2: If the two slots are to be used simultaneously, the max, dimension supported is 191 x 111.15 x 14.47 mm for each PCI expansion card. Note 3: The max, power consumption of PCI expansion card supported is 75W.

Ordering Information

| Part No. | Desription | PCIe x 16 | PCIe x 4 | PCI | NVMe | RAID 0/1 |
|----------------|--|-----------|----------|-----|------|----------|
| TPC-B610H-A00A | Intel [®] 10th Gen. Core™ i CPU Socket (LGA1200), H420E | 1 | NA | 1 | NA | NA |
| TPC-B610W-A00A | Intel [®] 10th Gen. Core™ i CPU Socket (LGA1200), W480E | 1 | 1 | NA | Yes | Yes |

Processor (TDP 35W)

| CPU | i7-10700TE | i5-10500TE | i3-10100TE | G6400TE | G5900TE |
|-----------------|------------|------------|------------|----------|----------|
| Cores | 8 | 6 | 4 | 2 | 2 |
| Base Frequency | 2.00 GHz | 2.30 GHz | 2.30 GHz | 3.20 GHz | 3.00 GHz |
| Turbo Frequency | 4.40 GHz | 3.70 GHz | 3.60 GHz | N/A | N/A |

Processor (TDP 65W)****

| CPU | i7-10700E | i5-10500E | i3-10100E | G6400E (58W) | G5900E (58W) |
|-----------------|-----------|-----------|-----------|--------------|--------------|
| Cores | 8 | 6 | 4 | 2 | 2 |
| Base Frequency | 2.90 GHz | 3.10 GHz | 3.20 GHz | 3.80 GHz | 3.20 GHz |
| Turbo Frequency | 4.50GHz | 4.20 GHz | 3.80 GHz | N/A | N/A |

Panel Module

| P/N | FPM-D15T-BE | FPM-D17T-BE | FPM-D15W-FBE | FPM-D18W-BE | FPM-D21W-BE | FPM-D24W-BE |
|--|----------------------|----------------------|-----------------------|----------------------|-----------------------|-----------------------|
| Description | 15" XGA TFT LED LCD | 17" SXGA TFT LED LCD | 15.6" FHD TFT LED LCD | 18.5" HD TFT LED LCD | 21.5" FHD LED LCD | 23.8" FHD TFT LED LCD |
| Dimension w/ TPC-B610 (L x W x H) (mm) | 383.2 x 328.3 x 97.5 | 410.4 x 364.4 x 98.3 | 419.7 x 290 x 100.3 | 488 x 330 x 100.3 | 558.4 x 370.8 x 100.3 | 595.9 x 395.1 x 100.3 |

| Panel Module P/N | FPM-D15T-CE | FPM-D15T-HE | FPM-D17T-CE | FPM-D19T-CE | FPM-D15W-FCE |
|---|--|--|-----------------------|--|-----------------------|
| Description | 15" XGA TFT LED LCD | 15" XGA TFT LED LCD High Brightness 1800 nits | 17" SXGA TFT LED LCD | 19" SXGA TFT LED LCD | 15.6" FHD TFT LED LCD |
| | | | | | |
| Panel Module P/N | FPM-D15W-FHE | FPM-D18W-FCE | FPM-D21W-CE | FPM-D21W-HE | FPM-D24W-CE |
| Description | 15.6" FHD TFT LED LCD High Brightness 1200 nits | 18.5" HD TFT LED LCD | 21.5" FHD TFT LED LCD | 21.5" FHD TFT LED LCD High brightness 1400 nits | 23.8" FHD TFT LED LCD |
| For more information about the panel module, please refer to "FPM-Display Module" Data Sheet. | | | | | |

Packing List

| Item | Part No. | Depiction | Qty |
|------------------------------|----------------|---|-----|
| Grounding cable | 1703011001-11 | A Cable G-TEM 4.3 100CM C=GR/Y | 1 |
| Plug-In Block | 1652006277-01 | PLUG-IN BLOCK 4P 5.08mm 90D(F) DIP | 1 |
| Plug-In Block | 1652006941-01 | Plug 2P 3.5mm 180D(F) MC420-35002ZY | 1 |
| Grease | 2170000093-01 | GREASE X23-7762 0.5+/- 0.15g | 1 |
| DDR Thermal-Pad | 1990021847N000 | Thermal-Pad PAD 64x24.5x2.0 K=6 GR-Hm SPC-1 | 1 |
| NVMI Thermal-Pad | 1990037589N000 | Thermal-Pad 60x15x3 K=6 Apus-GR-Hm | 1 |
| DDR Thermal-Pad | 1990031076N000 | Thermal-Pad 65x18x1.0 K=6 Apus-GR-Hm | 2 |
| M.2 & mini iPCIE Thermal-Pad | 1990027303N000 | Thermal-Pad 39X29.5X1.5 K=6 TP GR-Hm Snap on_A8 | 2 |
| Warranty | 2190000902 | CARDBOARD-WARRANTY REV. A2 | 1 |
| HDD Mylar | 1990037172T000 | Mylar HDD 104x70x0.15 for TPC-B610 | 2 |
| BOX Fix Screw | 1930030800 | Screw M3x8L S/S D=4.9 H=1 (2+) ST Ni | 5 |
| VESA Screw | 1930005204 | Screw M4x10L R/S DH=6.8x2.50 + ST ZBK PL | 4 |
| China rohs | 202KAKMC00 | China rohs for AKMC model name 1st ed | 1 |

Optional Accessories

- 96PSA-A230W24P4-3 230W 24V_{DC} Power Supply
- 1702002600 Power cable (US) 1.8 M
- **1702002605** Power cable (EU) 1.8 M
- 1702031801 Power cable (UK) 1.8 M
- 1700000596-11 Power cable (China/Australia) 1.8 M

Embedded OS

| Win10 IoT Enterprise LTSC 2021 for Entry (G5900TE/E) Win10 IoT Enterprise LTSC 2021 for Value (Core i3/i5, G6400TE/E) Win10 IoT Enterprise LTSC 2021 for High (Core i7) Win 11 IoT Ent LTSC 2024 for Entry (G5900TE/E) Win 11 IoT Ent LTSC 2024 for Value (Core i3/i5, G6400TE/E) Win 11 IoT Ent LTSC 2024 for High (Core i7) |
|--|
| Advantech Linux. V3.4.3 for TPC-B610 Series |
| |
| |

iDoor Modules

- PCM-24S2WF-BE 802.11 a/b/g/n/ac 2T2R w/BT4.1, Atheros QCA6174A
- PCM-24D2R4-BE Isolated RS-422/485, DB9 x 2, (USB type)
- Isolated RS-232, DB9 x 2, (USB type) PCM-24D2R2-BE
- PCM-24R1TP-BE 1-Port Gigabit Ethernet, Intel® 82574L, mPCIe, RJ45
- PCM-27D24DI-AE Digital I/O, 16 DI / 8 DO, Isolation, DB37 x 1
- PCM-26D2CA-AE 2-Port Isolated CANBus mPCIe, CANOpen, DB9
- PCM-24R2PE-AE Intel i350, GbE, PoE IEEE 802.3af, PD, RJ45 x 2
- *For TPC-B610, "PCM-28P1AD" is needed for iDoor module installation.

**iDoor module ocuppies one PCI expansion slot.

For more information about iDoor Module, please find "Advantech iDoor Module" on Advantech's official website. * CPU Power was limited to 35W via BIOS default for fanless support.

Application Software

HMINavi Designer is a powerful and intuitive software program for creating comprehensive human machine interface solutions. HMINavi Designer is an easily integrated development tool with proven value in many application fields. The features include solutionoriented screen objects, high-end vector graphics, Windows fonts for multi-language applications, receipts, alarm functions, as well as data and operation logging capabilities. HMINavi Designer also supports utility programs such as Data Transfer Helper (DTH), recipe editor, and text editor. The HMINavi **HMINavi** Designer software is free download for usage, user can directly download before purchase. With online/ offline simulation user can directly connect to PLC controller to ensure solid connection and screen design without any issue. HMINavi Runtime, a component of HMINavi, guarantees the reliability and performance of Open Platform because of the minimum system overhead, high data communication rates, sub-second screen switching, and 24/7 operation. Additionally, Advantech's fast response software team is continually adding new functions, communication drivers, and solutions to the software to meet dynamic needs.

Please note: If some optional modules are offered with the system, additional system certificates may be required in certain regions/countries. Please contact Advantech for certificate compliance.